DATA SHEET

Solid State Relay OCMOS FET

PS7122A-1A,-2A,PS7122AL-1A,-2A

6, 8-PIN DIP, 250 V BREAK DOWN VOLTAGE 1-ch, 2-ch Optical Coupled MOS FET

DESCRIPTION

NEC

The PS7122A-1A, -2A and PS7122AL-1A, -2A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity. The PS7122AL-1A, -2A have a surface mount type lead.

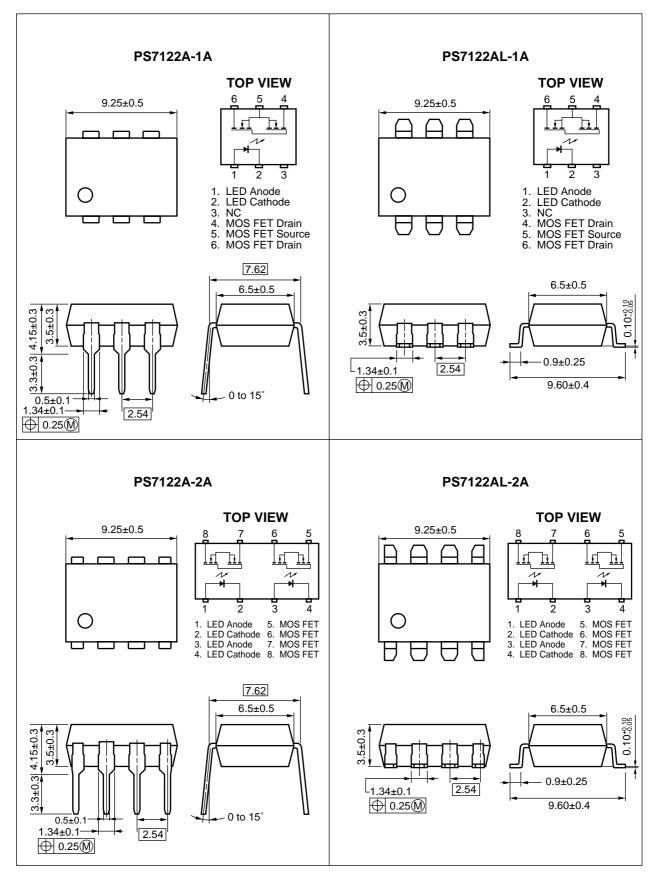
***** FEATURES

- 1 channel type (1 a output) or 2 channel type (1 a + 1 a output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- Small package (6, 8-pin DIP)
- · Low offset voltage
- PS7122AL-1A, -2A: Surface mount type
- UL approved: File No. E72422 (S)
- BSI approved: No. 8245/8246
- CSA approved: No. CA 101391

APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment





***** ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS7122A-1A	6-pin DIP	Magazine case 50 pcs	PS7122A-1A
PS7122AL-1A			PS7122AL-1A
PS7122AL-1A-E3		Embossed Tape 1 000 pcs/reel	
PS7122AL-1A-E4			
PS7122A-2A	8-pin DIP	Magazine case 50 pcs	PS7122A-2A
PS7122AL-2A			PS7122AL-2A
PS7122AL-2A-E3		Embossed Tape 1 000 pcs/reel	
PS7122AL-2A-E4			

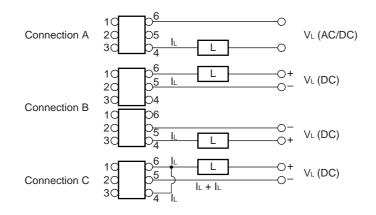
*1 For the application of the Safety Standard, following part number should be used.

Parameter				Rati		
			Symbol	PS7122A-1A, PS7122AL-1A	PS7122A-2A, PS7122AL-2A	Unit
Diode	le Forward Current (DC) Reverse Voltage		lf	50		mA
			Vr	5.0		V
Power Dissipation		PD	50		mW/ch	
	Peak Forward Current [™]		IFP	1		А
MOS FET	DS FET Break Down Voltage		VL	250		V
	Continuous	Connection A	lı.	200		mA
	Load Current ^{*2}	Connection B		350	-	
		Connection C		500	-	
	Pulse Load Current ^{*3} (AC/DC Connection)		Ilp	400		mA
	Power Dissipation		PD	560	375	mW/ch
Isolation Voltage ^{*4}			BV	1 500		Vr.m.s.
Total Power Dissipation			Рт	610	850	mW
Operating Ambient Temperature			TA	-40 to +80		°C
Storage Temperature			Tstg	-40 to +100		°C

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

*1 PW = 100 μ s, Duty Cycle = 1 %

*2 Conditions: IF \geq 2 mA. The following types of load connections are available.



*3 PW = 100 ms, 1 shot

*4 AC voltage for 1 minute at $T_A = 25$ °C, RH = 60 % between input and output

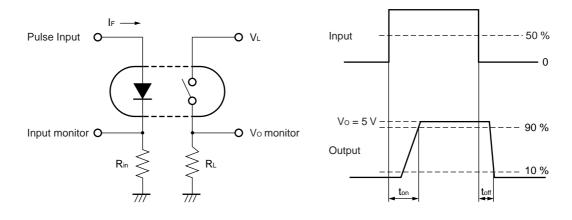
RECOMMENDED OPERATING CONDITIONS (TA = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

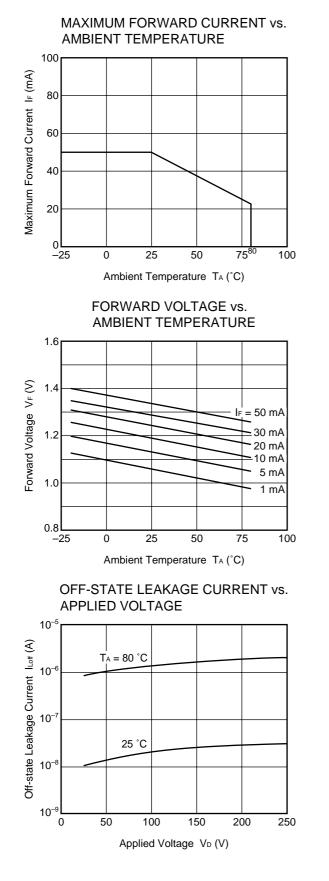
***** ELECTRICAL CHARACTERISTICS (TA = 25 °C)

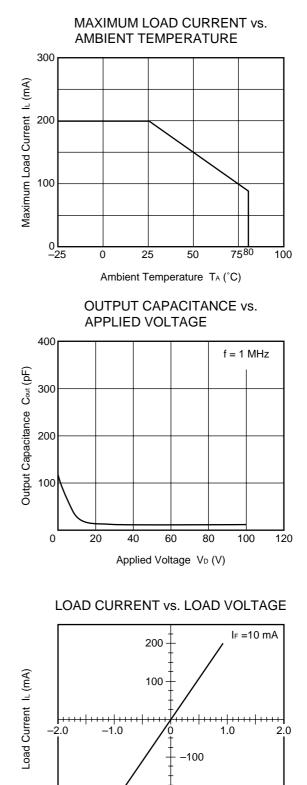
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	de Forward Voltage		IF = 10 mA		1.2	1.4	V
	Reverse Current	Ir	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V _D = 250 V		0.03	1.0	μA
	Output Capacitance	Cout	$V_{D} = 0 V, f = 1 MHz$		120		pF/ch
Coupled	LED On-state Current	IFon	I∟ = 200 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 10 mA		4.5	8.0	Ω
		Ron2	I_F = 10 mA, I_L = 200 mA, $t \leq$ 10 ms				
	Turn-on Time ^{*1}	ton	I_F = 10 mA, Vo = 5 V, PW \geq 10 ms		0.5	1.5	ms
	Turn-off Time ^{*1}	toff			0.04	0.2	
	Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10 [°]			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1 MHz		1.1		pF/ch

*1 Test Circuit for Switching Time



★ TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)



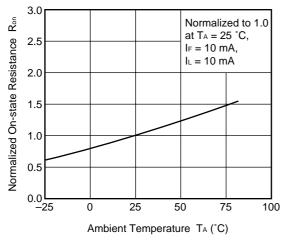


Load Voltage V_L (V)

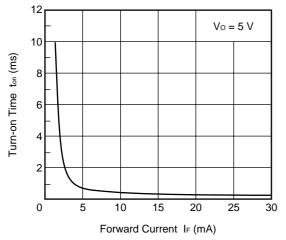
-200

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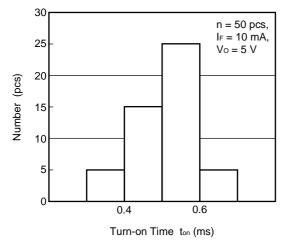
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE

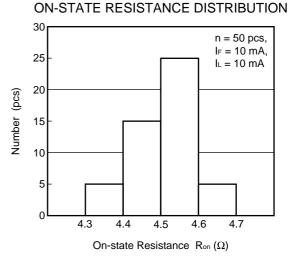


TURN-ON TIME vs. FORWARD CURRENT

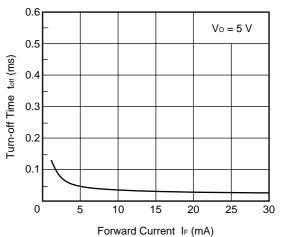


TURN-ON TIME DISTRIBUTION

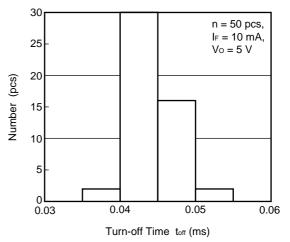


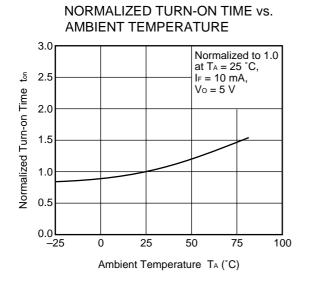


TURN-OFF TIME vs. FORWARD CURRENT

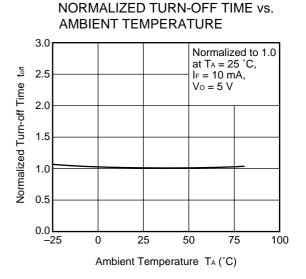


TURN-OFF TIME DISTRIBUTION

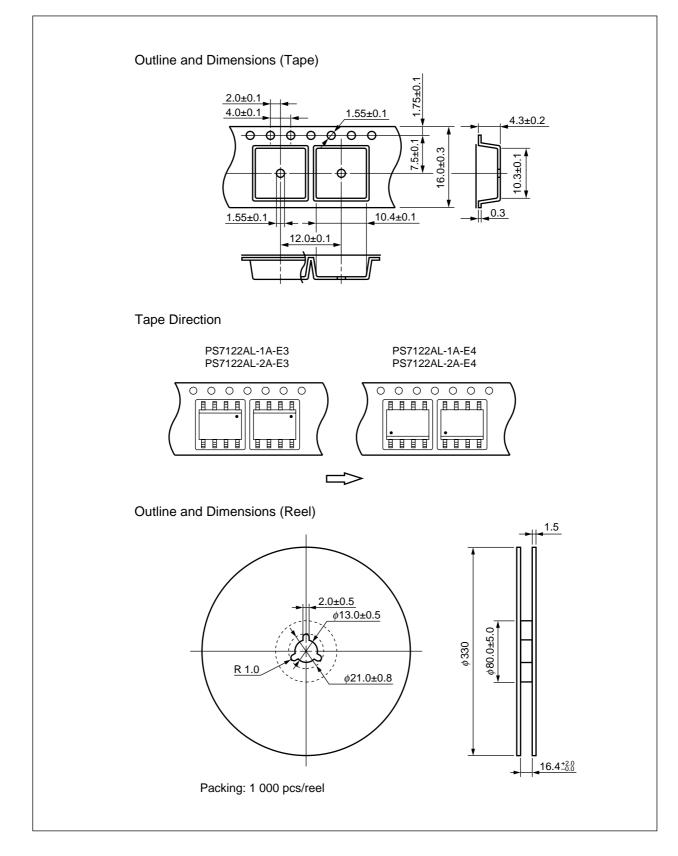




Remark The graphs indicate nominal characteristics.



***** TAPING SPECIFICATIONS (in millimeters)



RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

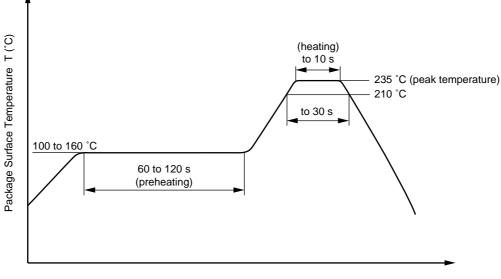
- Peak reflow temperature
 235 °C (package surface temperature)
- Time of temperature higher than 210 °C
- Number of reflows
- Flux

Two Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow

30 seconds or less





(2) Dip soldering

• Temperature 260 °C or below (molten solder temperature)

- Time
 - e 10 seconds or less
- Number of times One
- Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

(3) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

[MEMO]

CAUTION

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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